L Number	Hits	Search Text	DB	Time stamp
1	364	copper with plating with anneal\$3	USPAT;	2004/09/27 15:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
2	7560	anneal\$3 with remov\$3 with (top surface layer)	USPAT;	2004/09/27 15:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
3	19	(connect with plating with appeal (2) come (connect 2 with	IBM_TDB	2004/00/27 16:00
3	19	(copper with plating with anneal\$3) same (anneal\$3 with remov\$3 with (top surface layer))	USPAT;	2004/09/27 16:08
		remov\$3 with (top surface layer))	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
4	913	438/672.ccls.	USPAT;	2004/09/27 16:09
•	313	130,072.00.01	US-PGPUB	2001/03/27 10:03
5	390	438/678.ccls.	USPAT;	2004/09/27 16:08
, -			US-PGPUB	
6	1288	438/687.ccls.	USPAT;	2004/09/27 16:08
		•	US-PGPUB	, , , , , , , , , , , , , , , , , , , ,
7	98	257/E23.161.ccls.	USPAT;	2004/09/27 16:09
			US-PGPUB	
8	345	438/672.ccls. and (repeat\$3 again)	USPAT;	2004/09/27 16:09
!			US-PGPUB	
9	159	438/678.ccls. and (repeat\$3 again)	USPAT;	2004/09/27 16:09
İ			US-PGPUB	
10	535	438/687.ccls. and (repeat\$3 again)	USPAT;	2004/09/27 16:10
			US-PGPUB	
11	38	257/E23.161.ccls. and (repeat\$3 again)	USPAT;	2004/09/27 16:10
			US-PGPUB	